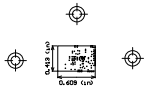
SYM	REVISIONS
X0	ECN DCM03_AFE4403_MCU 11/25/13 MPK

VIEWED FROM TOP SIDE



Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
O	98	6mil (0.152mm)	PTH	Round
□	22	9.685mil (0.246mm)	PTH	Round
	120 Total			

Drill Table

TEXAS INSTRUMENTS INC.
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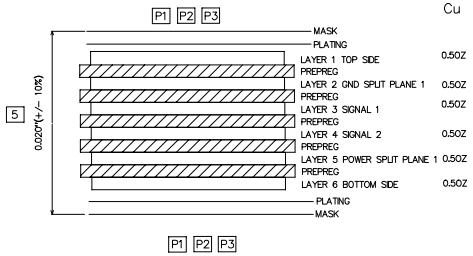
DCM03_AFE4403_MCU
PCB REV X0
FAB DRAWING
SHEET 1 OF 13
25-NOV-2013

ALL UNITS ARE INCHES UNLESS OTHERWISE SPECIFIED.

DETAIL A
SCALE:NONE
LAYER STACKUP



THIS IS A NON IMPEDANCE BOARD.

GENERAL NOTES: (UNLESS OTHERWISE SPECIFIED)

1. FABRICATE PER TI SPECIFICATION 6501320-LATEST REVISION EXCEPT AS NOTED BELOW.
2. LAMINATE MATERIAL FR4 .
3. COPPER WEIGHT: 0.5 OZ ON ALL LAYERS
4. MAXIMUM ALLOWABLE LINE REDUCTION TO BE 20% OR 0.002" WHICHEVER IS GREATEST.
5. FINISHED BOARD THICKNESS: 0.020" +/-10% SEE DETAIL A.
6. HOLE POSITION ACCURACY: +/-0.0015"
7. ALL PTH HOLES TO BE PLATED THROUGH 0.001" MIN COPPER.
8. BOARD WARP AND TWIST TO BE WITHIN 0.005" PER LINEAR INCH.
9. MINIMUM ANNULAR RING OF PLATED-THRU HOLES TO BE 0.002"
10. BOARD DIMENSION : 0.600"X 0.410"
11. ALL 0.006" VIAS NEED TO BE FILLED WITH NON-CONDUCTIVE EPOXY-RESIN AND PLATEOVER WITH COPPER.
    SURFACE MUST BE FLAT,FLATNESS TOLERANCE IS +0.000/-0.001" ON TOP SIDE ONLY AND +0.000/-0.003 ON BOTTOM SIDE.
    MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.
12. FOR 0.009" VIA DRILL TOLERANCE SHOULD BE +0/-0.0009".
13. 9.685 MIL DRILL TOLERANCE SHOULD BE +/-0.002".
14. 9.685 MIL PTH HOLES NEED TO BE PLATED ON BOARD EDGE AT 22 PLACES.

PROCESS NOTES:

P1 SOLDERMASK BOTH SIDES PER ARTWORK: GREEN LPI
   SOLDERMASK CLEARANCE IS GIVEN AS SAME AS PAD SIZE FOR ALL SMT
   COMPONENT. VENDOR SHALL OVERSIZE THE MASK CLEARANCE
   AS PER THEIR MANUFACTURING CAPABILITIES
P2 SILKSCREEN BOTH SIDES PER ARTWORK: COLOR=WHITE
P3 PLATING/PLATE CIRCUITRY ON OUTER LAYERS TO 5-15 MICRO INCHES AU OVER MINIMUM OF 200 MICRO INCHES NI. KNOOP HARDNESS 130-200.

MATERIAL:	PROCESSES:	
SEE NOTES	SEE NOTES	NEXT ASSEMBLY

TOLERANCES UNLESS OTHERWISE SPECIFIED			SURFACE ROUGHNESS
LINEAR		MISCELLANEOUS	
MILLIMETERS: XX +/- .25, X +/- .50	INCHES: XXX +/- .010, XX +/- .020	ANGLES +/- 1° AXIS OF TAPPED HOLES 90° +/- 1° REMOVE ALL BURRS & SHARP EDGES	THIRD ANGLE PROJECTION
HOLES			
MILLIMETERS: XXX +/- .076, XX +/- .127	INCHES: XXX +/- .003, XX +/- .005		

DRAFTSMAN: SIVAKUMAR	DATE: 11/25/13	TEXAS INSTRUMENTS INC. SEMICONDUCTOR OPERATIONS	CODE IDENTITY NUMBER 01295
DESIGNER: SIVAKUMAR	DATE: 11/25/13	TITLE: FABRICATION	
CHECKER: QA TESSOLVE	DATE: 11/25/13	DCM03_AFE4403_MCU	
ENGINEER: PRAVEEN	DATE: 11/25/13		
APPROVED: PRAVEEN	DATE: 11/25/13		
RELEASED: MIKE HORSON	DATE: 11/25/13	SCALE N / D SIZE / DCM03_AFE4403_MCU / X0 REV / SHEET 1	

WO#305848-5776-D